Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L1	1063	445/25,24,23.ccls. and (plastic\$4 flexib\$6 organic resin polymer\$6) and (thin\$4 blast\$4 sand\$blast\$3 abrad\$4 abrat\$3 ablat\$4 grind\$4 etch\$4 draw\$4 erod\$4 reduc\$4 heat\$4 bak\$4 evaporat\$4 shrink\$4 wear\$4 polish\$4 rough\$4 scratch\$4 smooth\$4 corros\$4)	USPAT; USOCR; EPO; JPO; DERWENT	OR	ON	2005/07/26 08:40
L2	1063	"445"/25,24,23.ccls. and (plastic\$4 flexib\$6 organic resin polymer\$6) and (thin\$4 blast\$4 sand\$blast\$3 abrad\$4 abrat\$3 ablat\$4 grind\$4 etch\$4 draw\$4 erod\$4 reduc\$4 heat\$4 bak\$4 evaporat\$4 shrink\$4 wear\$4 polish\$4 rough\$4 scratch\$4 smooth\$4 corros\$4)	USPAT; USOCR; EPO; JPO; DERWENT	OR	ON	2005/07/26 08:40
L3	807	"445"/25,24,23.ccls. and (plastic\$4 flexib\$6 organic resin polymer\$6) and (thin\$4 blast\$4 sand\$blast\$3 abrad\$4 abrat\$3 ablat\$4 grind\$4 etch\$4 draw\$4 erod\$4 reduc\$4 heat\$4 bak\$4 shrink\$4 wear\$4 polish\$4 rough\$4 corros\$4) and (remov\$4 sacrific\$4 supplement\$4)	USPAT; USOCR; EPO; JPO; DERWENT	OR	ON	2005/07/26 08:42
L4	645	"445"/25,24,23.ccls. and (plastic\$4 flexib\$6 organic resin polymer\$6) and (thin\$4 blast\$4 sand\$blast\$3 abrad\$4 abrat\$3 ablat\$4 grind\$4 etch\$4 draw\$4 erod\$4 reduc\$4 heat\$4 bak\$4 shrink\$4 wear\$4 polish\$4 rough\$4 corros\$4) and (remov\$4 sacrific\$4 supplement\$4) with (substrate panel film layer panel display)	USPAT; USOCR; EPO; JPO; DERWENT	OR	ON	2005/07/26 08:43
L5	554	"445"/25,24,23.ccls. and (plastic\$4 flexib\$6 organic resin polymer\$6) and (thin\$4 blast\$4 sand\$blast\$3 abrad\$4 abrat\$3 ablat\$4 grind\$4 etch\$4 draw\$4 erod\$4 reduc\$4 heat\$4 bak\$4 shrink\$4 wear\$4 polish\$4 rough\$4 corros\$4) and (remov\$4 sacrific\$4 supplement\$4) near5 (substrate panel film layer panel display)	USPAT; USOCR; EPO; JPO; DERWENT	OR	ON	2005/07/26 08:44

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L6	72	"445"/25,24,23.ccls. and (plastic\$4 flexib\$6 organic resin polymer\$6) and (thin\$4 blast\$4 sand\$blast\$3 abrad\$4 abrat\$3 ablat\$4 grind\$4 etch\$4 draw\$4 erod\$4 reduc\$4 heat\$4 bak\$4 shrink\$4 wear\$4 polish\$4 rough\$4 corros\$4) and (sacrific\$4 supplement\$4) near5 (substrate panel film layer panel display)	USPAT; USOCR; EPO; JPO; DERWENT	OR	ON	2005/07/26 08:45
L7	90	"445"/25,24,23.ccls. and (plastic\$4 flexib\$6 organic resin polymer\$6) and (thin\$4 blast\$4 sand\$blast\$3 abrad\$4 abrat\$3 ablat\$4 grind\$4 etch\$4 draw\$4 erod\$4 reduc\$4 heat\$4 bak\$4 shrink\$4 wear\$4 polish\$4 rough\$4 corros\$4) and (sacrific\$4 supplement\$4 temporary) near5 (substrate panel film layer panel display)	USPAT; USOCR; EPO; JPO; DERWENT	OR	ON	2005/07/26 10:19
L8	1	"445"/25,24,23.ccls. and (plastic\$4 flexib\$6 organic resin polymer\$6) and (thin\$4 blast\$4 sand\$blast\$3 abrad\$4 abrat\$3 ablat\$4 grind\$4 etch\$4 draw\$4 erod\$4 reduc\$4 heat\$4 bak\$4 shrink\$4 wear\$4 polish\$4 rough\$4 corros\$4) and (sacrific\$4 supplement\$4 temporary) adj (substrate)	USPAT; USOCR; EPO; JPO; DERWENT	OR	ON	2005/07/26 10:49
L9	146164	"438"/\$.ccls.	USPAT; USOCR; EPO; JPO; DERWENT	OR	ON	2005/07/26 09:03
L10	4972	"438"/\$.ccls. and (sacrific\$4 supplement\$4 temporary) near4 (substrate layer film panel device)	USPAT; USOCR; EPO; JPO; DERWENT	OR	ON	2005/07/26 09:04
L11	1951	"438"/\$.ccls. and (sacrific\$4 supplement\$4 temporary) near4 (substrate layer film panel device) and (plastic\$4 flexib\$6 organic resin polymer\$6)	USPAT; USOCR; EPO; JPO; DERWENT	OR	ON	2005/07/26 09:16
L12	71	"445"/25,24,23.ccls. and (process manufact\$6) and (plastic\$4 flexib\$6 organic resin polymer\$6) and (thin\$4 blast\$4 sand\$blast\$3 abrad\$4 abrat\$3 ablat\$4 grind\$4 etch\$4 draw\$4 erod\$4 reduc\$4 heat\$4 bak\$4 shrink\$4 wear\$4 polish\$4 corros\$4) and (sacrific\$4 supplement\$4) near5 (substrate panel film layer panel display)	USPAT; USOCR; EPO; JPO; DERWENT	OR	ON	2005/07/26 09:15

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L13	1951	"438"/\$.ccls. and (sacrific\$4 supplement\$4 temporary) near4 (substrate layer film panel device) and (plastic\$4 flexib\$6 organic resin polymer\$6) and (remov\$4 sacrific\$4 supplement\$4 temporary)	USPAT; USOCR; EPO; JPO; DERWENT	OR	ON	2005/07/26 09:18
L14	0	"438".ccls. and (sacrific\$4 supplement\$4 temporary) near4 (substrate layer film panel device) and (plastic\$4 flexib\$6 organic resin polymer\$6) and (remov\$4 sacrific\$4 supplement\$4 temporary) near3 (layer film panel display substrate)	USPAT; USOCR; EPO; JPO; DERWENT	OR	ON	2005/07/26 09:38
L15	1951	"438"/\$.ccls. and (sacrific\$4 supplement\$4 temporary) near4 (substrate layer film panel device) and (plastic\$4 flexib\$6 organic resin polymer\$6) and (remov\$4 sacrific\$4 supplement\$4 temporary)	USPAT; USOCR; EPO; JPO; DERWENT	OR	ON	2005/07/26 09:49
L16	1950	"438"/\$.ccls. and (sacrific\$4 supplement\$4 temporary) near4 (substrate layer film panel device) and (plastic\$4 flexib\$6 organic resin polymer\$6) and (remov\$4 sacrific\$4 supplement\$4 temporary) and (method process manufactur\$4)	USPAT; USOCR; EPO; JPO; DERWENT	OR	ON	2005/07/26 09:50
L17	1950	"438"/\$.ccls. and (sacrific\$4 supplement\$4 temporary) near4 (substrate layer film panel device) and (plastic\$4 flexib\$6 organic resin polymer\$6) and (method process manufactur\$4)	USPAT; USOCR; EPO; JPO; DERWENT	OR	ON	2005/07/26 09:51
L18	2	("0626655").PN.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/07/26 10:06
L19	2	("6866555").PN.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/07/26 10:06

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L20	45	"445"/25,24,23.ccls. and (plastic\$4 flexib\$6 organic resin polymer\$6) and (thin\$4 blast\$4 sand\$blast\$3 abrad\$4 abrat\$3 ablat\$4 grind\$4 etch\$4 draw\$4 erod\$4 reduc\$4 heat\$4 bak\$4 shrink\$4 wear\$4 polish\$4 rough\$4 corros\$4) and (sacrific\$4 supplement\$4 temporary) adj (substrate panel film layer panel display)	USPAT; USOCR; EPO; JPO; DERWENT	OR	ON	2005/07/26 10:23
L21	102	"445"/25,24,23.ccls. and (plastic\$4 flexib\$6 organic resin polymer\$6) and (thin\$4 blast\$4 sand\$blast\$3 abrad\$4 abrat\$3 ablat\$4 grind\$4 etch\$4 draw\$4 erod\$4 reduc\$4 heat\$4 bak\$4 shrink\$4 wear\$4 polish\$4 rough\$4 corros\$4) and (remov\$4 sacrific\$4 supplement\$4 temporary) adj (substrate panel film layer panel display)	USPAT; USOCR; EPO; JPO; DERWENT	OR	ON	2005/07/26 10:20
L22	76	"445"/25,24,23.ccls. and (plastic\$4 flexib\$6 organic resin polymer\$6) and (thin\$4 blast\$4 sand\$blast\$3 abrad\$4 abrat\$3 ablat\$4 grind\$4 etch\$4 draw\$4 erod\$4 reduc\$4 heat\$4 bak\$4 shrink\$4 wear\$4 polish\$4 rough\$4 corros\$4) and (sacrific\$4 supplement\$4 temporary) near3 (substrate panel film layer panel display)	USPAT; USOCR; EPO; JPO; DERWENT	OR	ON	2005/07/26 10:37
L23	2	("0000156").PN.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/07/26 10:37
L24	0	"156"/\$.ccls	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/07/26 10:37
L25	144806	"156"/\$.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/07/26 10:37
L26	26377	"156"/\$.ccls. and (substrate panel display) and (plastic\$4 flexib\$6 organic resin polymer\$6)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON .	2005/07/26 10:38

L27	22778	"156"/\$.ccls. and (substrate panel display) and (plastic\$4 flexib\$6 organic resin polymer\$6)	USPAT; USOCR; EPO; JPO; DERWENT	OR .	ON	2005/07/26 10:39
L28	5814	"156"/\$.ccls. and (substrate panel display) and (plastic\$4 flexib\$6 organic resin polymer\$6) and (remov\$4 sacrific\$4 supplement\$4 temporary) near3 (substrate panel display film layer)	USPAT; USOCR; EPO; JPO; DERWENT	OR	ON	2005/07/26 10:40
L29	8795	"156"/\$.ccls. and (plastic\$4 flexib\$6 organic resin polymer\$6) and ((remov\$4 sacrific\$4 supplement\$4 temporary) near3 (substrate panel display film layer)) and (thin\$4 blast\$4 sand\$blast\$3 abrad\$4 abrat\$3 grind\$4 etch\$4 draw\$4 erod\$4 reduc\$4 heat\$4 bak\$4)	USPAT; USOCR; EPO; JPO; DERWENT	OR	ON	2005/07/26 10:47
L30	6462	"156"/\$.ccls. and (plastic\$4 flexib\$6 organic resin polymer\$6) and ((remov\$4 sacrific\$4 supplement\$4 temporary) near3 (substrate panel display film layer)) and (thin\$4 blast\$4 sand\$blast\$3 abrad\$4 abrat\$3 grind\$4 etch\$4 draw\$4 erod\$4 reduc\$4 heat\$4 bak\$4) near3 (substrate panel display film layer)	USPAT; USOCR; EPO; JPO; DERWENT	OR	ON	2005/07/26 10:56
L31	32	"445"/25,24,23.ccls. and (plastic\$4 flexib\$6 organic resin polymer\$6) and (remov\$4 sacrific\$4 supplement\$4 temporary) adj (substrate)	USPAT; USOCR; EPO; JPO; DERWENT	OR	ON	2005/07/26 10:50
L32	32	"445"/25,24,23.ccls. and (plastic\$4 flexib\$6 organic resin polymer\$6) and ((remov\$4 sacrific\$4 supplement\$4 temporary) adj (substrate))	USPAT; USOCR; EPO; JPO; DERWENT	OR	ON	2005/07/26 10:55
L33	1	"445"/25,24,23.ccls. and (plastic\$4 flexib\$6 organic resin polymer\$6) and ((sacrific\$4 supplement\$4 temporary) adj (substrate))	USPAT; USOCR; EPO; JPO; DERWENT	OR	ON	2005/07/26 10:55
L34	1786	"156"/\$.ccls. and (plastic\$4 flexib\$6 organic resin polymer\$6) and ((remov\$4 sacrific\$4 supplement\$4 temporary) near3 (substrate)) and (thin\$4 blast\$4 sand\$blast\$3 abrad\$4 abrat\$3 grind\$4 etch\$4 draw\$4 erod\$4 reduc\$4 heat\$4 bak\$4) near3 (substrate panel display film layer)	USPAT; USOCR; EPO; JPO; DERWENT	OR ·	ON	2005/07/26 12:27

L35	364	"156"/\$.ccls. and (plastic\$4 flexib\$6 organic resin polymer\$6) adj (panel	USPAT; USOCR;	OR .	ON	2005/07/26 11:11
		substrate) and ((remov\$4 sacrific\$4 supplement\$4 temporary) near3 (substrate)) and (thin\$4 blast\$4 sand\$blast\$3 abrad\$4 abrat\$3 grind\$4 etch\$4 draw\$4 erod\$4 reduc\$4 heat\$4 bak\$4) near3 (substrate panel display film layer)	EPO; JPO; DERWENT			
L36	23	"445"/25,24,23.ccls. and (plastic\$4 flexib\$6 organic resin polymer\$6) adj (panel substrate) and ((remov\$4 sacrific\$4 supplement\$4 temporary) near3 (substrate)) and (thin\$4 blast\$4 sand\$blast\$3 abrad\$4 abrat\$3 grind\$4 etch\$4 draw\$4 erod\$4 reduc\$4 heat\$4 bak\$4) near3 (substrate panel display film layer)	USPAT; USOCR; EPO; JPO; DERWENT	OR	ON	2005/07/26 11:14
L37	343	"156"/154,153,155,344,247.ccls. and (plastic\$4 flexib\$6 organic resin polymer\$6) and ((remov\$4 sacrific\$4 supplement\$4 temporary) near3 (substrate)) and (thin\$4 blast\$4 sand\$blast\$3 abrad\$4 abrat\$3 grind\$4 etch\$4 draw\$4 erod\$4 reduc\$4 heat\$4 bak\$4) near3 (substrate panel display film layer)	USPAT; USOCR; EPO; JPO; DERWENT	OR	ON	2005/07/26 12:31
L38	1879	"156"/154,153,155,344,247.ccls. and (plastic\$4 flexib\$6 organic resin polymer\$6) and ((melt\$4 brat\$3 ablat\$4 grind\$4 etch\$4 draw\$4 erod\$4 reduc\$4 heat\$4 bak\$4 abrad\$4 blast\$4 remov\$4 sacrific\$4 supplement\$4 temporary) near3 (substrate panel display film layer))	USPAT; USOCR; EPO; JPO; DERWENT	OR	ON	2005/07/26 13:01
L39	2	("6866555").PN.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/07/26 12:51
L40	2	("6824437").PN.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/07/26 12:51

L41	316	"156"/154,153,155,344,247.ccls. and (plastic\$4 flexib\$6 organic resin polymer\$6) near3 substrate and ((melt\$4 brat\$3 ablat\$4 grind\$4 etch\$4 draw\$4 erod\$4 reduc\$4 heat\$4 bak\$4 abrad\$4 blast\$4 remov\$4 sacrific\$4 supplement\$4 temporary) near3 (substrate))	USPAT; USOCR; EPO; JPO; DERWENT	OR	ON	2005/07/26 13:47
L42		("5954906").PN.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/07/26 13:47